



REPLACEMENT SHEET  
Multi-Layered Barrier Metal Thin Films for Cu Interconnect by ALCVD  
Serial No.: 09/819,296  
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Fig. 1

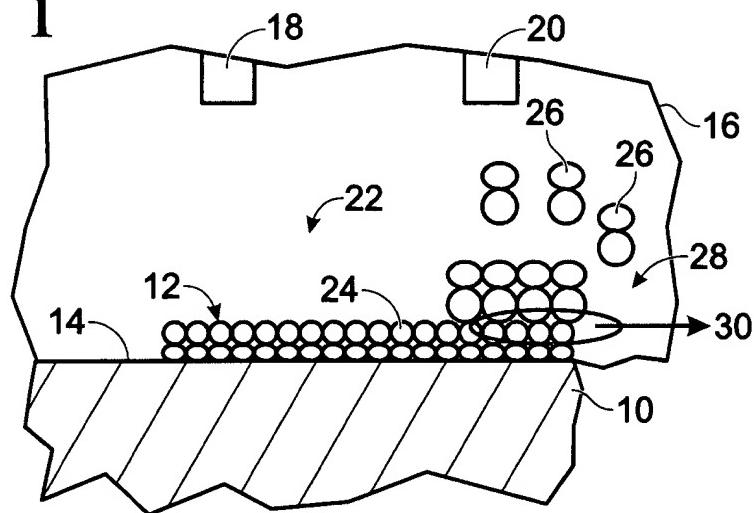


Fig. 2

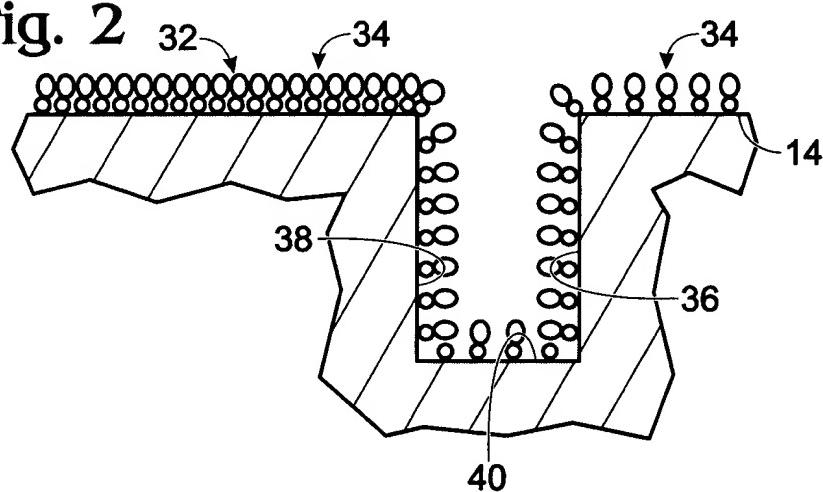


Fig. 3

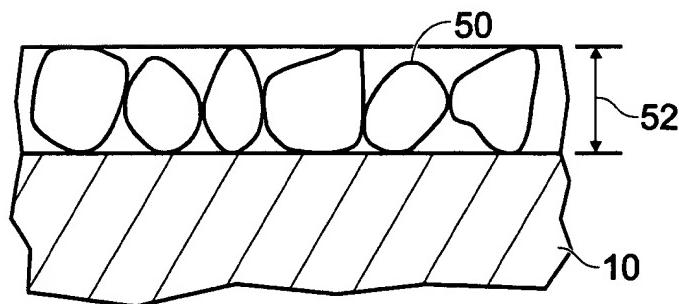


Fig. 4

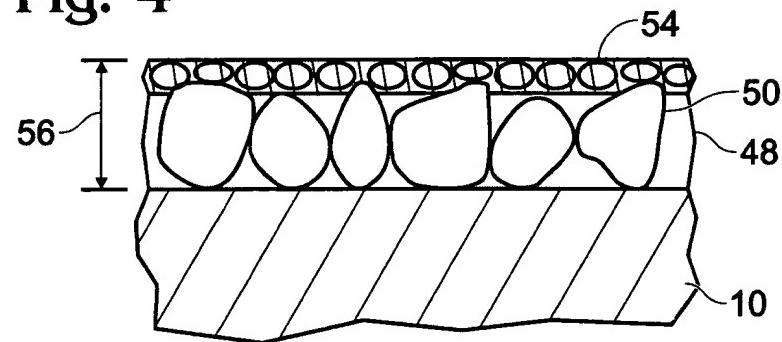


Fig. 5

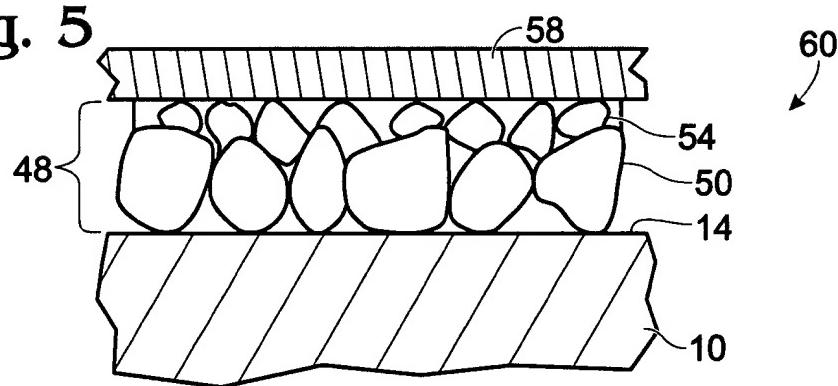


Fig. 6

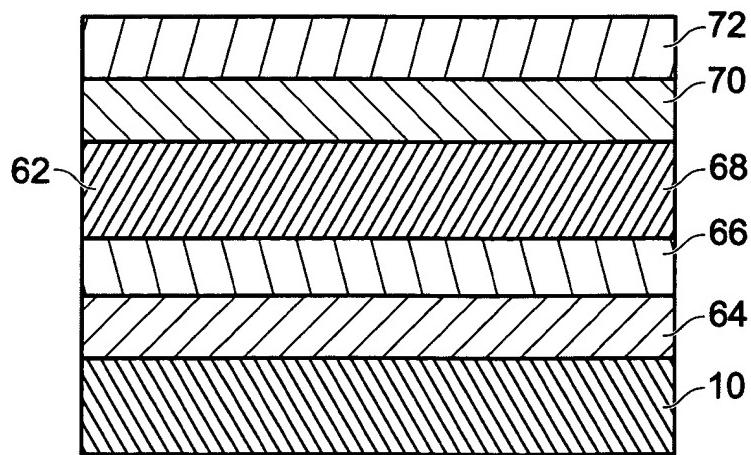


Fig. 7

